

Title (en)

LAYERED COMPOSITE WITH AN INSULATION LAYER

Title (de)

SCHICHTVERBUND MIT EINER ISOLATIONSSCHICHT

Title (fr)

COMPOSITE STRATIFIÉ COMPRENANT UNE COUCHE D'ISOLATION

Publication

**EP 1313681 A2 20030528 (DE)**

Application

**EP 01969630 A 20010822**

Priority

- DE 10041554 A 20000824
- EP 0109702 W 20010822

Abstract (en)

[origin: WO0216919A2] The invention relates to a layered composite with an insulation layer for the electrical insulation of a first layer from a second layer. The first layer is embodied as a first oxygen ion conducting solid electrolyte layer or a first electrically conducting layer and the second layer is embodied as a second oxygen ion conducting solid electrolyte layer or a second electrically conducting layer. The insulation layer is formed on a support from a ceramic powder and/or a glass powder, by means of a paste or a suspension, whereby the first layer at least partly, or the second layer at least partly serves as support and the sintered insulation layer has a layer thickness of  $\leq 10 \mu\text{m}$ . The aim of the invention is to prepare a further layered composite with an insulation layer, in particular for an exhaust sensor. Said aim is achieved for the layered composite, whereby the powder used for the insulation layer is a nanopowder with a specific surface area as determined by BET of  $> 50 \text{ m}^2/\text{g}$  and that the maximum powder particle size for the nanopowder is 100nm.

IPC 1-7

**C04B 35/626**

IPC 8 full level

**G01N 27/409** (2006.01); **B32B 7/02** (2006.01); **G01N 27/04** (2006.01); **G01N 27/407** (2006.01)

CPC (source: EP US)

**B82Y 30/00** (2013.01 - EP US); **G01N 27/4071** (2013.01 - EP US)

Citation (search report)

See references of WO 0216919A2

Designated contracting state (EPC)

AT BE CH DE FR GB LI

DOCDB simple family (publication)

**WO 0216919 A2 20020228; WO 0216919 A3 20020808;** DE 10041554 A1 20020321; DE 10041554 C2 20030227; EP 1313681 A2 20030528; JP 2004507380 A 20040311; US 2002175076 A1 20021128

DOCDB simple family (application)

**EP 0109702 W 20010822;** DE 10041554 A 20000824; EP 01969630 A 20010822; JP 2002521964 A 20010822; US 11135802 A 20020424